



Product Specification

Product:	Conductive Copper Paste
Part Number:	25H-1805

Substrate	Ceramic material	
Usage Method	250-350 mesh screen printing	
Leveling	Level at room temperature for 3-5 minutes (time adjusted according to actual leveling conditions)	
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).	
Firing Condition	<p>The sintering temperature of the tunnel furnace under the nitrogen protective atmosphere is 830±10°C (recommended value) and the sintering time is 10-20 minutes.</p> <p>The sintering range can be adjusted within 800-850°C according to actual requirements, but the peak temperature duration must be at least 10 minutes. Generally, ceramic capacitors exhibit superior performance after high-temperature sintering compared to low-temperature sintering.</p>	
Viscosity	120-240Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements.
Solid Content	80%	Copper
Resistivity	≤15mΩ/□	Square resistance test The cured film thickness is 10μm, and the test pattern size is 100mm*1mm.
	≤5mΩ/□	Four-pin probe method 25.4 μU
Adhesion	Not fall off	≥36.2N

Application Scope :

This product is suitable for copper electrode of ceramic capacitor.

Usage Conditions :

Substrate	Ceramic material
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).



Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).
Firing Condition	The sintering temperature of the tunnel furnace under the nitrogen protective atmosphere is 830±10°C (recommended value) and the sintering time is 10-20 minutes. The sintering range can be adjusted within 800-850°C according to actual requirements, but the peak temperature duration must be at least 10 minutes. Generally, ceramic capacitors exhibit superior performance after high-temperature sintering compared to low-temperature sintering.
Thinner	ST-1000

Characteristics :**1. Paste Characteristics :**

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤5μm	FOG test
2 Viscosity	120-240Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R, operating at 10rpm and 25±1°C, with adjustable viscosity according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.

Check fired film produced under the conditions specified in 1) , (Film thickness is 8-12μm.)

Characteristics	Standard	Test Method And Conditions
3 Resistivity	≤15mΩ/□	Test pattern 0.6mm×60mm
4 Adhesion Strength		Peel Test: 0.5mm φ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
Initial Adhesion	≥36.2N	

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g per can.

Sample weight: 200 g/can